

Product Technical Data Sheet

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AG Gold

AG Gold is a high-quality thermal conductive paste. Owing to its gold content, its thermal conductivity is 3 times higher than in the case of regular pastes. This allows the processor to lower the processor temperature by about 6 degrees, even without changing the radiator. The paste is the best alternative for overclockers.

Application:

- fills micro-inequalities between the touching elements, e.g. processor and radiator
- perfect as a substance transferring heat from the condenser tubes to the exchanger in the vacuum solar collector.

Properties:

Parameters	UoM	Result
Colour	-	gold
Thermal conductivity	W/mK	> 2.8
Thermal impedance	°C in2/W	< 0.095
Specific weight	g/cm ³	> 2.5
Evaporation	-	< 0.001
Ingress	-	< 0.05
Dielectric constant	-	> 5.1
Viscosity	-	does not flow
Thixotropic index	-	380+/-10
Operating temperature	°C	-30-300
Momentary resistance to temperature	°C	-50-340

Packagings:

Volume	Collective packaging	Item Code
1 g (syringe)	5	ART.AGT-163
3 g (syringe)	5	ART.AGT-106
100 g (jar)	1	ART.AGT-119
100 ml (aerosol)	4	ART.AGT-145

Warehousing:

Store in a well-ventilated, cool and dry place. Keep containers tightly closed when not in use. Protect against sunlight exposure.

Data contained in this document are consistent with the current state of our knowledge. They describe typical product properties and applications. However, it is up to the user to examine the suitability of this product for specific applications. We deny liability for the obtained results on the grounds that application conditions lie beyond our control.